

IN THE CLAIMS

1-12. (*Canceled*).

13. (*Currently Amended*) A method for megasonic cleaning of semiconductor wafers comprising the steps of:

generating two or more parallel sets of megasonic waves in a cleaning fluid, the megasonic waves having a common direction of travel and ~~wave fronts~~
5 ~~that are generally perpendicular to the direction of travel~~;

immersing ~~semiconductors~~ the wafers in the cleaning fluid; and
moving the wafers in the cleaning fluid through two or more of said
megasonic waves in a direction that is generally perpendicular to the direction of travel of the megasonic waves and generally perpendicular to ~~the wave fronts of~~
10 a plane parallel with the megasonic waves.

14. (*Currently Amended*) The method of claim 13 wherein the megasonic waves are generated across parallel regions of the fluid and the step of moving the wafers comprises reciprocating the wafers through at least two of said parallel regions.

15. (*Previously Presented*) A method for megasonic cleaning of semiconductor wafers disposed within a holder, the holder and wafers disposed in a cleaning fluid within a container, the method comprising the steps of:

- generating megasonic waves in the cleaning fluid;
- 5 intercepting the generated waves inside the container at a location between one or more sources of the megasonic waves and the holder, and dispersing the waves in a divergent manner; and
- exposing the semiconductor wafers to the dispersed megasonic waves within the cleaning fluid.

16-26. (*Canceled*).

27. (*Currently Amended*) A method for megasonic cleaning of semiconductor wafers comprising the steps of:

- generating two or more parallel sets of megasonic waves in a cleaning fluid;
- 5 immersing ~~semiconductors~~ the wafers in the cleaning fluid such that faces of the wafers are parallel with the waves; and
- moving the wafers in the cleaning fluid through said megasonic waves in a direction that is generally transverse to perpendicular to the megasonic waves and generally perpendicular to the faces of the wafers.